

Product Roadmap

2026 Q2

RUGGED EMBEDDED SYSTEM

Harsh Environments and
Mission-Critical Application



ARK-I 2I640PW+ DM003



ROCK 2I130HW



SealPro - 2I130HW



SealPro - 3I140HW



TERA M12



HAWK 3I130TW



MIL-STD-810G
Certified

EXTREME TEMP



Anti
Vibration

SHOCK & VIBRATION RESISTANT

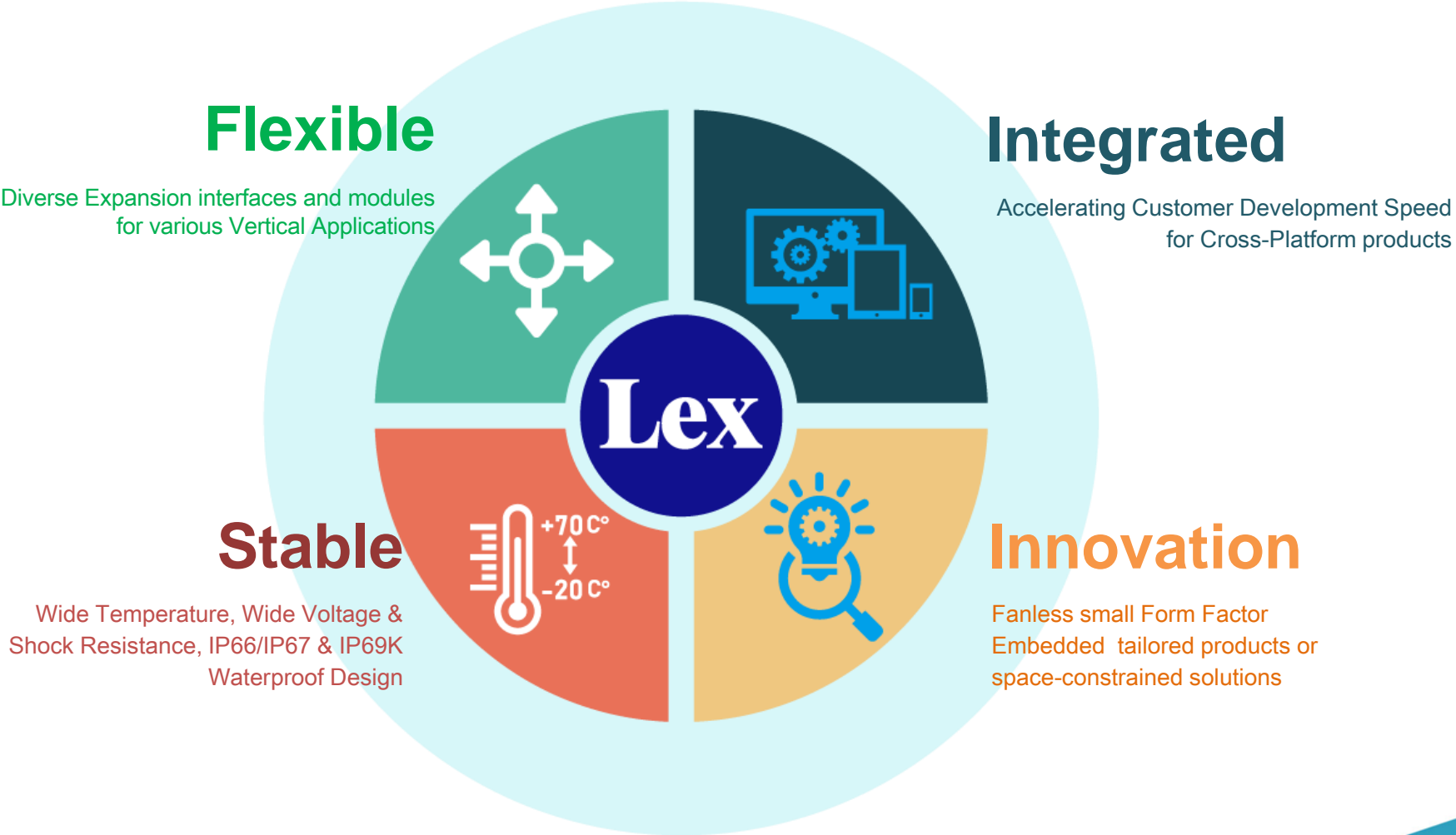


Lex SYSTEM®

Contents

- LEX System Features & Advantages
- Embedded Solution Overview
- Embedded Solution Case Study
- Product Highlights
- Product Development Timeline
- Product long term supply
- Contact Information

Features & Advantages



Flexible

Diverse Expansion interfaces and modules for various Vertical Applications

Integrated

Accelerating Customer Development Speed for Cross-Platform products

Stable

Wide Temperature, Wide Voltage & Shock Resistance, IP66/IP67 & IP69K Waterproof Design

Innovation

Fanless small Form Factor Embedded tailored products or space-constrained solutions

LEX SYSTEM – Embedded Solution

LEX offers design and manufacturing of industrial motherboards, industrial computers, expansion boards, and customized industrial computers, including edge computing systems and AI intelligent application platforms. Our in-house developed products cover four major categories:



1 Embedded IPC Board

- Single Board Computer
- CPU board
- Computer On Module
- UPS board
- ARM-based SBC



2 Customized Motherboard & Chassis

Innovating Research & Integration Services for Global OEM/ODM and System Integrators

• Applications



AI / Visual Analytics



Smart Manufacturing /
Machine Vision



IoT / IIoT



Smart Healthcare/
AI Medical Imaging



Smart Transportation &
Railways



Maritime Shipping
& Navigation



Defense / Military
Robust Computers



Networking/
Communication Equipment



Edge Computing
Edge Gateway Control

LEX SYSTEM – Embedded Solution



3 Fanless Rugged Panel PC, Fanless Embedded Systems, Servers



4 Expansion Boards/Cards & Related Accessories

Fanless Rugged Panel PC



•SUPER series (7"/10.1"/10.4"/15")



•VITA series (10.1"/15"/21.5"/23.8")



•Slim series (8.4"/10.2"/15.1"/17")



•SHARK IP66/67 **waterproof** (10.1"/13.3")



•STAR IP66/67 **waterproof** (10.4"/12.1"/15.1")



•**Stainless** IP66/IP67/IP69K **waterproof**

(10.4"/15.1"/19")

Fanless Embedded System



•Rugged /Waterproof System



•In-vehicle System

•DIN Rail System



•1U server

•AI image Analysis & Machine Vision

•Ultra Compact / Compact System

•High-Speed Ethernet Network Card / PoE / Fiber Card

•4G / 5G / WiFi / Bluetooth Module

•Video Capture Card

•USB / SIM / COM / Display Conversion Card

•M.2 / eIO Expansion Card

•Storage Card

•Digital IO Card

•Carriers and Converter Boards

•Power Boards and Charger Modules

Embedded Solution— Case Study



Spain
Intelligent Transportation
Surveillance System



China
Highway ETC smarting
billing system



Germany
3D Surgery Navigation



China
Servotronics EtherCAT
Robot Motion Control

Embedded Solution— Case Study



Kiosk-Self Service
Harsh outdoor Panel PC
for Winter Olympics



Video Analysis
Metro Real-time
Surveillance System



Poland
Railway in-train
communication



Netherlands
Fleet management

2026 Q2 Product Highlights

31160DW-3.5" SBC



Intel® Core™ Ultra CPU
(Panther Lake)
2 x HDMI®, LVDS/eDP, 1 X Type C
2 x DDR5 SODIMM Max 96 GB
5 x Intel 2.5 GbE, 3 x USB 3.2, 5 x USB 2.0
3 x M.2, 1 x Nano SIM, 1 x PCIe x2, 2 x PCIe x4
HD Audio, 3 x MIPI-CSI, 4 x COM, 4DI / 4DO

21140D-2.5" SBC



Intel® Core™ Ultra CPU
(Meteor Lake-U/H) (Arrow Lake-U/H)
HDMI®, eDP
Onboard LPDDR5 16 / 32GB
4 x Intel 2.5 GbE, 3 x USB 3.2, 4 x USB 2.0
2 x M.2, 1 x Nano SIM, 2 x COM, 4DI / 4DO

31140HW-3.5" SBC



Intel® Core™ Ultra CPU
(Meteor Lake-U/H) (Arrow Lake-U/H)
DP, HDMI®, LVDS / DP
2 x DDR5 SODIMM Max 64GB
3 x Intel 2.5 GbE, 4 x USB 3.2, 3 x USB 2.0
3 x M.2, 1 x Nano SIM, HD Audio
4 x COM, 4DI / 4DO, 2 X MIPI-CSI

21132DW-2.5" SBC



Intel® 13th Gen Raptor Lake-U CPU
Onboard LPDDR5, 16 / 32GB
HDMI®, eDP
4 x Intel 2.5 GbE, 3 x USB 3.2
4 x USB 2.0, 2 x COM, 4DI / 4DO,
2 x M.2, 1 x Nano SIM

21740DW-2.5" SBC



Intel® ATOM Amston Lake x7000 CPU
Onboard LPDDR5, Max 32GB
1 x HDMI®
3 x Intel 2.5 GbE, 3 x USB 3.2, 2 x USB 2.0
2 x M.2, 2 x COM

21740AW-2.5" SBC



Intel® ATOM Amston Lake x7000 CPU
1 x SODIMM DDR5, Max 16GB
HDMI®, 1 x Intel 2.5 GbE, 4 x COM
4 x USB 3.2, 2 x USB 2.0
2 x M.2, 1 x MINI SIM,

21740CW-2.5" SBC



Intel® ATOM Amston Lake x7000 CPU
1 x SODIMM DDR5, Max 16GB
HDMI®, Type C, LVDS
2 x Intel 2.5 GbE, 3 x USB 3.2, 2 x USB 2.0
1 x USB 3.2 Type C, 2 x M.2, 1 x Nano SIM
2 x MIPI-CSI, 4 x COM, 4DI/4DO

21642DW-2.5" SBC



Intel® ATOM
Elkhart Lake x6413E / J6412 CPU
Onboard LPDDR5, 16 / 32GB
2 x HDMI®, eDP 3 x Intel 2.5 GbE
2 x USB 3.0, 3 x USB 2.0
2 x M.2, 1 x Nano SIM,

Product Highlights (Embedded IPC Board)



2I130HW-2.5" Plus SBC
2I130DW-2.5" Plus SBC
3I130DW-3.5" Plus SBC
3I130TW-161x150 mm SBC



2I110D-2.5" Plus SBC
2I110AW-2.5" Plus SBC
3I110HW/BW-3.5" Plus SBC



2NOR01- 2.5" Plus carrier board
For Board for Edge Ail solution with
NVIDIA® Jetson Orin™ Nano (Super)NX

ORIN-TW

Carrier Board for Railway solution with
NVIDIA® Jetson Orin™ Nano(Super) / NX

2NOR02- compact carrier board
For Edge Ail solution with NVIDIA® Jetson
Orin™ Nano / NX

2NOR03- compact carrier board
For Edge Ail solution with NVIDIA® Jetson
Orin™ Nano / NX



3I470DW-155 x150 mm SBC



CI370D-217 x 185 mm SBC
CI371D-217 x 223 mm SBC
3I370DW-155 x130 mm SBC



2N8MP01- 2.5" Plus SBC

NXP-HAI02- -carrier board with Hailo AI chip
For Edge Ail solution with I.MX8M Plus CPU

NXP-HAI03 -carrier board with Hailo AI chip
For Edge Ail solution with I.MX8M Plus CPU



2I810D-2.5" Plus SBC
3I810DW-3.5" Plus SBC
3I810HW/BW-3.5" Plus SBC



2I640PW-Compute on Module
2I640HL-2.5"Plus SBC with Hailo-8
2I640DW-2.5"Plus SBC
2I640CW-2.5"Plus SBC
2I640HW-2.5"Plus SBC
2I640SW-2.5"Plus SBC
3I640DW-3.5" SBC
3I640CW-3.5" SBC

2026 Q2 Product Development timeline



Intel® Core™ Ultra CPU (Series 3)



31160DW

Intel® Core™ Ultra 300 Series (Panther Lake) processors

Revamped I GPU and integrated NPU

2 x DDR5 SODIMM, Max 96GB

Multiple Independent display: 2 x HDMI®, LVDS / eDP, 1 x Type C

5 x Intel 2.5 GbE LAN, 3 x USB 3.2 Gen1x1, 5 x USB 2.0,

1 x M.2 M Key, 2 x M.2 B Key, 1 x Nano SIM,

1 x PCIe x2, 2 x PCIe x 4

4 x COM, 4DI / 4DO, 3 x MIPI-CSI, HD Audio

TPM 2.0, SMBus, I2C, I2S

Dimension: 146 x 150 mm

2026 Q2 Product Development timeline



Intel® Core™ Ultra CPU



2I1140D

Intel® Core™ Ultra 7/5 Series processors
(Meteor Lake –U/H & Arrow Lake-U/H)

On board LPDDR5 16/32 GB

1 x HDMI®, eDP,

4 x Intel 2.5 GbE LAN, 3 x USB 3.2 Gen 1, 4 x USB 2.0

1 x M.2 M Key, 1 x M.2 B Key, 1 x Nano SIM

2 x COM, 4DI / 4DO, Audio (OEM)

TPM 2.0, SMBus, I2C, DC IN+ 12V

Dimension: 108 x 112 mm



3I1140DW

Intel® Core™ Ultra 7/5 Series processors
(Meteor Lake –U/H & Arrow Lake-U/H)

2 x DDR5 SODIMM, Max 64GB

1 x HDMI®, 1 x DP, LVDS, 1 x Type C

5 x Intel 2.5 GbE LAN, 3 x USB 3.2 Gen 1, 3 x USB 2.0

1 x M.2 M Key, 2 x M.2 B Key, 1 x Nano SIM, 1 x PCIe

4 x COM, 2 x CANBus, 4DI / 4DO, Audio

TPM 2.0, SMBus, I2C, I2S, Wide Range DC IN+9~36V

Dimension: 150 x 155 mm



HAWK 3I1140DW



3I140HW

Intel® Core™ Ultra 7/5 Series processors
(Meteor Lake –U/H & Arrow Lake-U/H)

2 x DDR5 SODIMM, Max 64GB

1 x HDMI®, LVDS, 1 x Type C

3 x Intel 2.5 GbE LAN, 4 x USB 3.2 Gen 1, 3 x USB 2.0

1 x M.2 M Key, 2 x M.2 B Key, 1 x Nano SIM, High Speed Connector (PCIe x2)

4 x COM, 2 x MIPI-CSI, 4DI / 4DO, Audio

TPM 2.0, SMBus, I2C, Wide Range DC IN+9~36V

Dimension: 146 x 150 mm

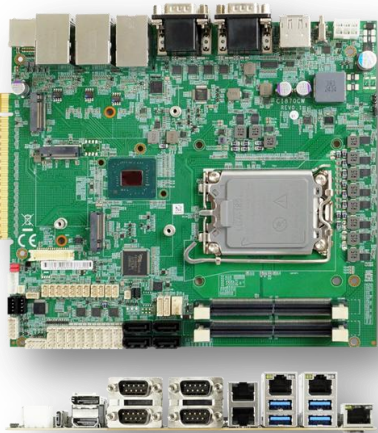


SealPro 3 I140HW

2026 Q2 Product Development timeline

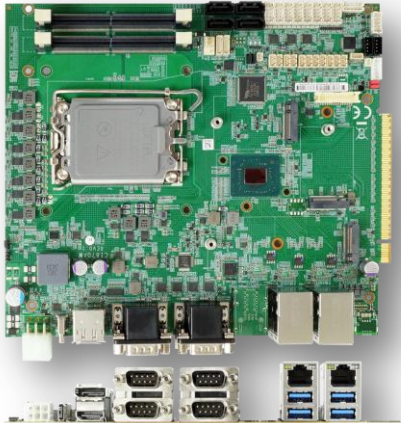


Intel® Core™ Ultra CPU



CI870CW

Intel® Core™ Ultra 7/5 (Arrow Lake-S) Series processors
2 x DDR5 SODIMM, Max 96 GB
Multiple Independent display:
1 x HDMI®, 1 x DP, 1 x eDP / LVDS, 1 x Type C
5 x Intel 2.5 GbE LAN, 4 x USB 3.2 Gen 1, 4 x USB 2.0
1 x M.2 M Key, 2 x M.2 B Key, 1 x Nano SIM, 1 x PCIe x16
10 x COM, 8DI / 8DO, Audio
TPM 2.0, SMBus, I2C, I2S
Wide Range DC IN+12~36V
Dimension: LEX form factor (186 x 217 mm)



CI870AW

Intel® Core™ Ultra 7/5 (Arrow Lake-S) Series processors
2 x DDR5 SODIMM, Max 96GB
Multiple Independent display:
1 x HDMI®, 1 x DP, 1 x Type C
2 x Intel 2.5 GbE LAN, 4 x USB 3.2 Gen 1, 4 x USB 2.0
1 x M.2 M Key, 2 x M.2 B Key, 1 x Nano SIM, 1 x PCIe x16
4 x COM, 8DI / 8DO, TPM 2.0, SMBus, I2C, I2S
Wide Range DC IN+12~36V
Dimension: LEX form factor (186 x 217 mm)



TWISTER(L)-CI870AW



TWISTER(L)-CI870CW



1U Fanless-CI870AW



1U Fanless-CI870CW

2026 Q2 Product Development timeline



13th Gen Intel® Core™ Raptor Lake-P/U



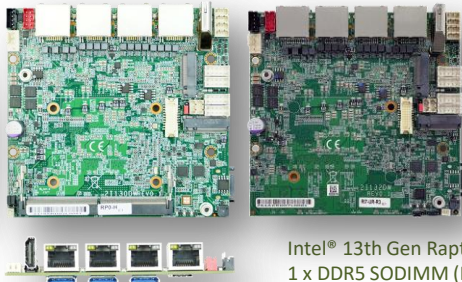
21130HW
 Intel® 13th Gen Raptor Lake-U/P CPU
 1 x DDR5 SODIMM (Max. 32GB)
 HDMI®, eDP, LVDS
 2 x Intel 2.5 GbE, 4 x USB 3.2
 4 x USB 2.0, 2 x COM, 4DI / 4DO,
 HD Audio, 1 x Mini PCIe, 1 x M.2
 108 x 102 mm



ROCK 21130HW



SealPro 21130HW



21130DW / 21132DW

Intel® 13th Gen Raptor Lake-U CPU
 1 x DDR5 SODIMM (Max. 32GB) -21130DW
 Onboard LPDDR5 16/ 32GB-21132DW
 HDMI®, eDP
 4 x Intel 2.5 GbE, 3 x USB 3.2
 4 x USB 2.0, 2 x COM, 4DI / 4DO,
 2 x M.2, 1 x Nano SIM
 108 x 102/ 108 x 105 mm



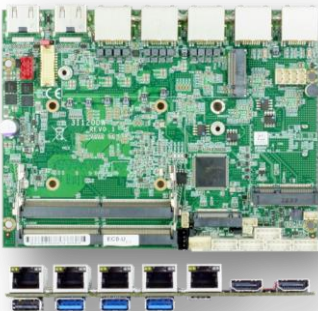
FOX 21130DW



SKY 2 21130DW



ROCK 21130DW



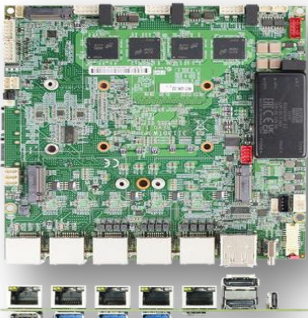
31130DW
 Intel® 13th Gen Raptor Lake-P / U CPU
 2 x DDR5 SODIMM (Max. 64GB)
 2 x HDMI®, eDP, 1 x Type C DP ALT Mode
 5 x Intel 2.5 GbE, 3 x USB 3.2, 5x USB 2.0
 1 x Mini PCIe, 2 x M.2, 1 x Nano SIM
 2 x COM, 4DI / 4DO
 146 x 110 mm



HAWK 31130DW



SKY 3 31130DW



31130TW
 Intel® 13th Gen Raptor Lake- U CPU
 On-board LPDDR5 (16GB/32 GB)
 HDMI®, DP, eDP, 5 x Intel 2.5 GbE,
 3 x USB 3.2, 3x USB 2.0, 3 x M.2,
 1 x Nano SIM, 2 x ISO-COM, HD Audio
 2 x ISO- CANBus, 4DI / 4DO, onboard NVMe
 CPC-Ignition Delay on/off control
 161 x 150 mm



HAWK 31130TW (M12)



Mobile Rack (Optional)

2026 Q2 Product Development timeline

NVIDIA Jetson Orin Nano(Super)/ NX SOM Carrier Board

JETSON
Orin™ NX

JETSON
Orin™ Nano



CPU Board:

NVIDIA Jetson NX: 8 / 16GB LPDDR5, 70 / 100 TOPs

NVIDIA Jetson Nano(Super): 4 / 8GB LPDDR5, 20 / 40 TOPs

AI Accelerator: NVIDIA® Jetson Orin™ Nano(Super) / Orin™ NX

2NOR02

1 x HDMI®, 1 x GbE
8 x USB 3.1, 1 x Type C USB 3.1 / 2.0 (OTG), 1 x USB 2.0
1 x RS232 (OEM to RS422)
1 x M.2 M key, 1 x M.2 B key, URAT, I2S, 2 x I2C



FOX 2NOR02

2NOR03

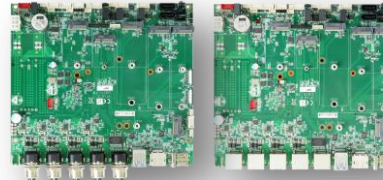
1 x HDMI®, 1 x GbE, 1 x 2.5GbE
2 x USB 3.1, 1 x Type C USB 3.1 / 2.0 (OTG)
1 x RS232 (OEM Option RS422)
1 x M.2 M key, 1 x M.2 B key
Support **8 X GMSL cameras**



FOX 2NOR03+GM04

ORIN-TW

1 x DP, 5 x GbE (1 + 4 x PoE)
1 x USB 3.1 Type C ; 2 x USB 3.1 Type A ; 1x USB 2.0
Mic-in / Line-out ; AMP 2W, 2 x SATA
2 x Isolated RS232 / RS422 / RS485, 1 x Isolated CANBus
1 x M.2 M key, 4 x M.2 B key, 1 x M.2 E Key, 1 x Nano SIM
2 x MIPI CSI, SPI, I2S, 3 x I2C, 8DI / 8 DO,
ISO Wide Range +9~36V, CPC-Ignition on/off delay control



HAWK ORIN-TW
M12 I/O / Mobile Rack (Optional)

2NOR01

1 x HDMI®, 2 x 2.5GbE, 1 x GbE
4 x USB 3.1, 1 x Type C USB 3.1 / 2.0 (OTG), 1 x USB 2.0
Mic-in / Line-out ; AMP 2W
2 x RS232 (Option RS422), 1 x CANBus
1 x M.2 M key 2 x M.2 B key, 1 x SIM, 4DI / 4DO
Internal wafer: SPI, I2S, I2C, USB 2.0



SKY 2NOR01

ROCK 2NOR01

2026 Q2 Product Development timeline



NXP i.MX8M Plus / ARM Cortex-A53

Ultra Compact solution
with Onboard Hailo-8™ AI processor



NXP-HAI02 / HAI03

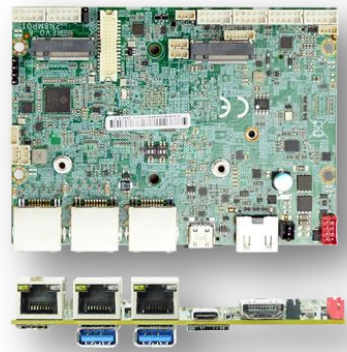
NXP i.MX8M Plus (Quad core) ARM Cortex-A53 CPU
LPDDR4, 8GB (NEX-8MP), 32-256GB eMMC 5.1 (NEX-8MP)
Mini HDMI®, 1 x USB 3.0 Type C, 1 x GbE (M12) or 2 x RJ45 ;
1 x USB 3.0 Type A, 1 x Micro SD,
M8 Connector: DC Power, LAN, DI/DO, RS485
Wide Range DC-IN +9-24V
Dimension: 66W x 94D x 30.8H mm



NXP-HAI02

NXP-HAI03

With NEX-8MP computer on module



2N8MP01

NXP i.MX8M Plus (Quad core)
ARM Cortex A53 + M7 CPU
LPDDR4, 4GB / 8GB
Independent display: 1 x HDMI®, LVDS,
3 x GbE LAN, 2 x USB 3.0, 3 x USB 2.0
2 x COM, 3 x M.2, 1 x Nano SIM, 1 x Type C USB 3.0 (OTG)
4DI / 4DO, 1 x MIPI (CSI), 1 x CANBus
115.4 x 84.5 mm



NET-II 2N8MP01

PALM-NEX001

NXP i.MX8M Plus (Quad core)
ARM Cortex A53 CPU
LPDDR4, 8GB (NEX-8MP)
32GB eMMC 5.1 (NEX-8MP),
expandable to 256GB
HDMI®, 2 x GbE; 2 x USB 3.0 / 2.0
1 x Micro SD, 1 x RS232, 1 x RS485
DC input : +5V
71.4W x 71.4D x 29.5H mm



MINI NXP-HAI02



MINI NXP-HAI03

2026 Q2 Product Development timeline



Intel® Amston Lake ATOM x7000 series processor

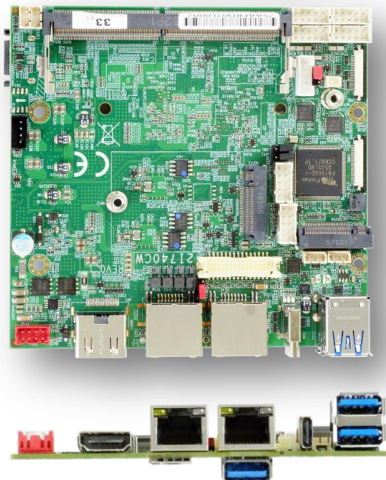


21740DW

Intel® ATOM Amston Lake x7000 series CPU
Onboard LPDDR5, Max 32GB
HDMI®, 3 x Intel 2.5 GbE, 3 x USB 3.2, 2 x USB 2.0
2 x M.2, 1 x Nano SIM, 2 x COM,
Wide Range DC-IN +9~24V
115.4 x 84.5 mm



NET-II 21740DW



21740CW

Intel® ATOM Amston Lake x7000 series CPU
1 x DDR5 SODIMM, Max. 16GB
HDMI®, Type C ALT, LVDS
2 x Intel 2.5 GbE, 3 x USB 3.2, 2 x USB 2.0
1 x USB3.2 Type C, 2 x MIPI-CSI, 4DI/4DO
2 x M.2, 4 x COM, Wide Range DC-IN +9~36V
108 x 102 mm



LEX Series Panel PC

2026 Q2 Product Development timeline

Expansion Card and Modules



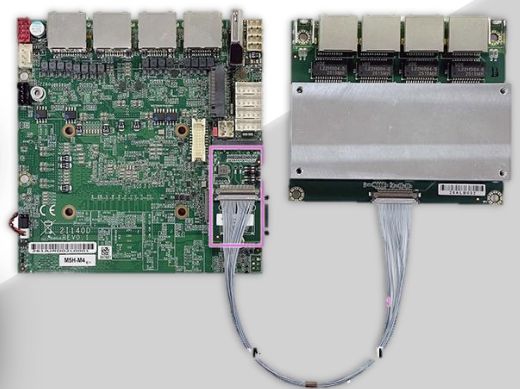
CU006
1 x USB convert to 4 x USB 3.0 HUB



CL210A
4 Port GbE LAN board



CL210P
4 Port PoE GbE LAN



Easy Expansion:
Connect the set to the SBC's M.2 B+M slot to enable 4 x GbE LAN / 4 x PoE LAN / 4 x USB 3.0

CN073 / CN075
M.2 B+M Key2242 /2280 connector board
Via USB3.2 Type A / USB 3.2 SSL / PCIe



PW505
Isolation power board
with CPC-Ignition on/off control
1.5KVDC I/O isolation
PW505-36: 9-36V in, 12V out, max 60W
PW505-75: 18-75V in, 12V out, max 60W



CC107
USB to 4 x ISO RS232/422/485



M504B
Mini PCIe to 4* RS232/485/422
(F81504U)



ADC002
Analog Input solution

LEX SYSTEM with Long-Term Supply

EOL Timeline	2028	2029	2030	2031	2032	2033	2034	2035	2036
Bay Trail	Q4								
Apollo Lake				Q3					
Elkhart Lake				Q1					
Amston Lake							Q2		
Skylake 6th			Q3						
Kaby Lake 7th					Q1				
Coffee Lake 8th						Q2			
Coffee Lake 9th							Q2		
Whisky Lake						Q3			
Comet Lake			Q2						
Tiger Lake UP3			Q3						
Raptor Lake						Q1			
Meteor Lake-U/H						Q4			
Arrow Lake-U			Q1						
Arrow Lake-S			Q1						
Panther Lake									Q1
Nova Lake									Q1
i.MAX 8M Plus								Q1	
Jetson Orin Nano NX			Q1						

* Product life span in alignment with Intel's IOTG / NVIDIA modules Life cycle /NXP CPU longevity.

Contact us

LEXCOM B.V.
(The Netherlands)

Tel:+31-73-6872390
Fax:+31-73-6872398
Email: info@lex.com.tw

LEX COMPUTECH CO.,LTD.
(Taiwan Taipei)

Tel:+886-2-2228-1055
Fax:+886-2-2228-1056
Email: lex.sales@lex.com.tw

LEX COMPUTECH CO.,LTD.
(South Korea)

Tel:+ 82-10-5936-4669
Email: yeon@lex.com.tw

CHINA Subsidiary
研毅通电子科技有限公司

Tel:+86-0512-65993318
+86 18500172031

E-mail: robin@yanyitong.com.cn

